

Title (en)

Method and device for applying RFID chips to a roll of material

Title (de)

Verfahren und Vorrichtung zum Bestücken einer Materialbahnrolle mit RFID-Chips

Title (fr)

Procédé et dispositif d'alimentation d'un rouleau de matériau en puces RFID

Publication

**EP 2388219 A3 20121219 (DE)**

Application

**EP 11158762 A 20110318**

Priority

- DE 102010029101 A 20100519
- DE 102010044154 A 20101119

Abstract (en)

[origin: EP2388219A2] The method involves loading a Radio frequency identification (RFID) chip (5,6) during the winding of a material web. The loading operation is performed at the beginning or at the end of the winding operation. The RFID-chip is embedded in an adhesive track. The material web is defined on the outer periphery of material web rolls. An independent claim is also included for an apparatus for loading a material web roll with radio frequency identification chip.

IPC 8 full level

**B65H 19/28** (2006.01); **B65H 19/29** (2006.01); **B65H 75/18** (2006.01)

CPC (source: EP)

**B65H 19/286** (2013.01); **B65H 19/29** (2013.01); **B65H 75/182** (2013.01); **B65H 2301/41484** (2013.01); **B65H 2511/12** (2013.01); **B65H 2553/52** (2013.01)

Citation (search report)

- [X] US 2003025027 A1 20030206 - EBISAWA RYOJI [JP], et al
- [X] EP 1803671 A2 20070704 - NRC INTERNAT INC [US]
- [X] EP 1947591 A1 20080723 - BROTHER IND LTD [JP]
- [X] EP 1538084 A1 20050608 - ISHIDA SEISAKUSHO [JP]

Cited by

US10507996B2; WO2016173857A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 2388219 A2 20111123; EP 2388219 A3 20121219**; CN 102275764 A 20111214; DE 102010044154 A1 20111124

DOCDB simple family (application)

**EP 11158762 A 20110318**; CN 201110130068 A 20110519; DE 102010044154 A 20101119